

### ***In The Claims***

Please cancel claim 4 without prejudice or disclaimer to the subject matter contained therein.

Please replace the claims as follows:

A2  
1. (Amended) A one system module in which a socket is placed between a ceramic PCB and an epoxy PCB that are disposed inside a module body, a power element and signal elements are respectively mounted on the upper portion of each PCB, wherein a groove is made at the lower side surface and at the middle side surface of the module body to support the ceramic PCB and the epoxy PCB to form a two-story structure, and a power pin for receiving a power signal from an external source is mounted on the upper portion of at least one edge of the ceramic PCB and a signal pin for receiving various signals from an external source is mounted on the upper portion of at least one edge of the epoxy PCB in line with the power pin.

A3  
3. (Amended) The one system module according to claim 1, wherein the power pin is mounted on the ceramic PCB by soldering, while the signal pin is mounted on the epoxy PCB by soldering.

Please add the following claims:

A4  
--5. The one system module according to claim 1, wherein power pins are mounted on the upper portion of both edges of the ceramic PCB and signal

pins are mounted on the upper portion of both edges of the epoxy PCB in line with the power pins.

6. A one system module comprising:

a module body, said module body including an inside surface having a first groove formed at a lower portion thereof and a second groove formed at a mid portion thereof;

a ceramic printed circuit board (PCB) supported in said first groove so as to be disposed inside said module body, said ceramic PCB having power elements secured thereto;

an epoxy PCB supported in said second groove so as to be disposed inside said module body, said epoxy PCB having signal elements secured thereto;

a socket located between said ceramic PCB and said epoxy PCB, said socket establishing electrical communications between said power elements of said ceramic PCB and said signal elements of said epoxy PCB;

a power pin mounted on an upper surface and along a first edge of said ceramic PCB, said power pin for receiving a power signal from a source external to said module body; and

a signal pin mounted on an upper surface and along a first edge of said epoxy PCB, said signal pin for receiving various signals from a source external to said module body, wherein said signal pin is linearly arranged relative to said power pin.

7. The one system module according to claim 6, wherein said power pin is a first power pin and said signal pin is a first signal pin, and further comprising:

a second power pin mounted on said upper surface and along a second edge of said ceramic PCB, wherein said second edge of said ceramic PCB is opposite said first edge of said ceramic PCB; and

a second signal pin mounted on said upper surface and along a second edge of said epoxy PCB, wherein said second edge of said epoxy PCB is opposite said first edge of said epoxy PCB.

8. The one system module according to claim 7, wherein said second signal pin is linearly arranged relative to said second power pin.

9. The one system module according to claim 6, wherein said signal elements include a microprocessor.

10. The one system module according to claim 9, wherein gold wire bonding is used to secure leads of said microprocessor to said epoxy PCB, and wherein aluminum wire bonding is used secure leads of said power elements to said ceramic PCB.

11. The one system module according to claim 10, wherein said power pin is mounted on said ceramic PCB by soldering, and said signal pin is mounted on said epoxy PCB by soldering.

12. The one system module according to claim 6, wherein said power pin is mounted on said ceramic PCB by soldering; and said signal pin is mounted on said epoxy PCB by soldering.--

---

44  
cancel